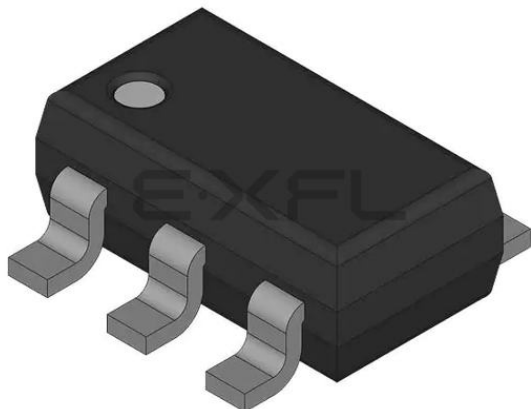




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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 6x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN-EP (4x4)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908qt2acfqe

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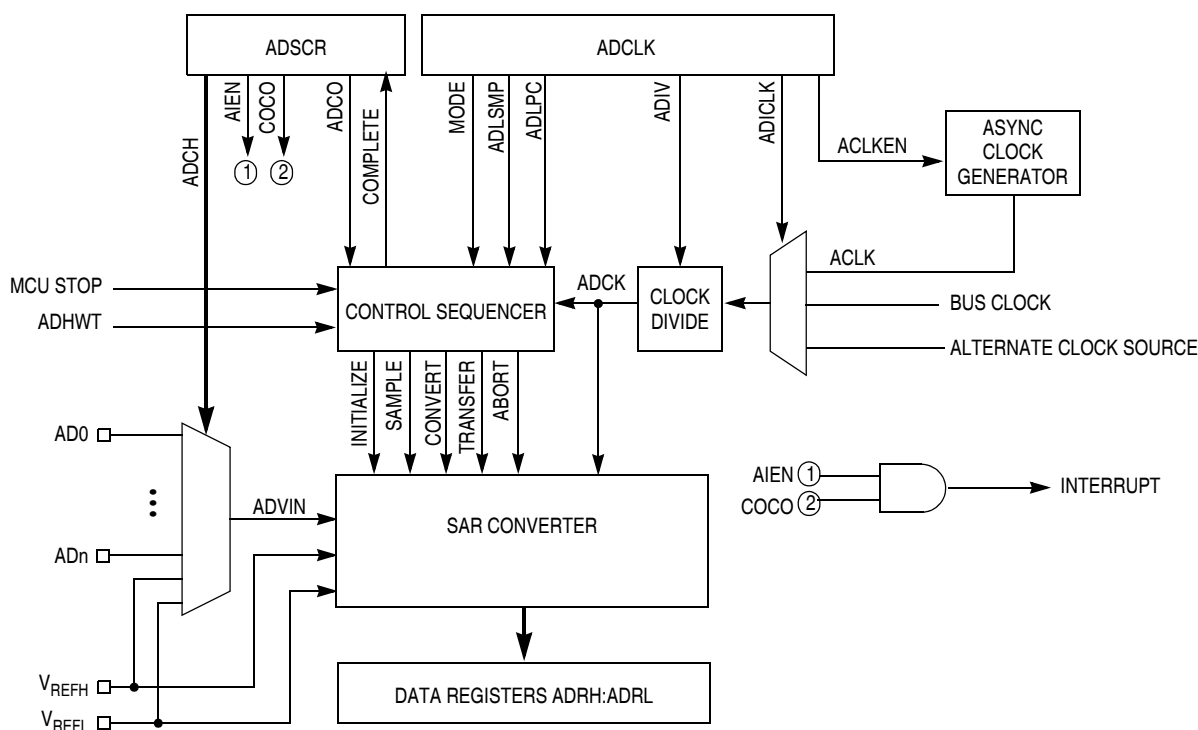


Figure 3-2. ADC10 Block Diagram

The ADC10 can perform an analog-to-digital conversion on one of the software selectable channels. The output of the input multiplexer (ADV_{IN}) is converted by a successive approximation algorithm into a 10-bit digital result. When the conversion is completed, the result is placed in the data registers (ADRH and ADRL). In 8-bit mode, the result is rounded to 8 bits and placed in ADRL. The conversion complete flag is then set and an interrupt is generated if the interrupt has been enabled.

3.3.1 Clock Select and Divide Circuit

The clock select and divide circuit selects one of three clock sources and divides it by a configurable value to generate the input clock to the converter (ADCK). The clock can be selected from one of the following sources:

- The asynchronous clock source (ACLK) — This clock source is generated from a dedicated clock source which is enabled when the ADC10 is converting and the clock source is selected by setting the ACLKEN bit. When the ADLPC bit is clear, this clock operates from 1–2 MHz; when ADLPC is set it operates at 0.5–1 MHz. This clock is not disabled in STOP and allows conversions in stop mode for lower noise operation.
- Alternate Clock Source — This clock source is equal to the external oscillator clock or a four times the bus clock. The alternate clock source is MCU specific, see [3.1 Introduction](#) to determine source and availability of this clock source option. This clock is selected when ADICLK and ACLKEN are both low.
- The bus clock — This clock source is equal to the bus frequency. This clock is selected when ADICLK is high and ACLKEN is low.

Whichever clock is selected, its frequency must fall within the acceptable frequency range for ADCK. If the available clocks are too slow, the ADC10 will not perform according to specifications. If the available

Upon reset or when a conversion is otherwise aborted, the ADC10 module will enter a low power, inactive state. In this state, all internal clocks and references are disabled. This state is entered asynchronously and immediately upon aborting of a conversion.

3.3.3.4 Total Conversion Time

The total conversion time depends on many factors such as sample time, bus frequency, whether ACLKEN is set, and synchronization time. The total conversion time is summarized in [Table 3-1](#).

Table 3-1. Total Conversion Time versus Control Conditions

Conversion Mode	ACLKEN	Maximum Conversion Time
8-Bit Mode (short sample — ADLSMP = 0):		
Single or 1st continuous	0	18 ADCK + 3 bus clock
Single or 1st continuous	1	18 ADCK + 3 bus clock + 5 μ s
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	16 ADCK
8-Bit Mode (long sample — ADLSMP = 1):		
Single or 1st continuous	0	38 ADCK + 3 bus clock
Single or 1st continuous	1	38 ADCK + 3 bus clock + 5 μ s
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	36 ADCK
10-Bit Mode (short sample — ADLSMP = 0):		
Single or 1st continuous	0	21 ADCK + 3 bus clock
Single or 1st continuous	1	21 ADCK + 3 bus clock + 5 μ s
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	19 ADCK
10-Bit Mode (long sample — ADLSMP = 1):		
Single or 1st continuous	0	41 ADCK + 3 bus clock
Single or 1st continuous	1	41 ADCK + 3 bus clock + 5 μ s
Subsequent continuous ($f_{Bus} \geq f_{ADCK}$)	X	39 ADCK

The maximum total conversion time for a single conversion or the first conversion in continuous conversion mode is determined by the clock source chosen and the divide ratio selected. The clock source is selectable by the ADICLK and ACLKEN bits, and the divide ratio is specified by the ADIV bits. For example, if the alternate clock source is 16 MHz and is selected as the input clock source, the input clock divide-by-8 ratio is selected and the bus frequency is 4 MHz, then the conversion time for a single 10-bit conversion is:

$$\text{Maximum Conversion time} = \frac{21 \text{ ADCK cycles}}{16 \text{ MHz}/8} + \frac{3 \text{ bus cycles}}{4 \text{ MHz}} = 11.25 \mu\text{s}$$

$$\text{Number of bus cycles} = 11.25 \mu\text{s} \times 4 \text{ MHz} = 45 \text{ cycles}$$

NOTE

The ADCK frequency must be between f_{ADCK} minimum and f_{ADCK} maximum to meet A/D specifications.



LVIPWRD — LVI Power Disable Bit

LVIPWRD disables the LVI module.

- 1 = LVI module power disabled
- 0 = LVI module power enabled

LVITRIP — LVI Trip Point Selection Bit

LVITRIP selects the voltage operating mode of the LVI module. The voltage mode selected for the LVI should match the operating V_{DD} for the LVI's voltage trip points for each of the modes.

- 1 = LVI operates for a 5-V protection
- 0 = LVI operates for a 3-V protection

NOTE

The LVITRIP bit is cleared by a power-on reset (POR) only. Other resets will leave this bit unaffected.

SSREC — Short Stop Recovery Bit

SSREC enables the CPU to exit stop mode with a delay of 32 BUSCLKX4 cycles instead of a 4096 BUSCLKX4 cycle delay.

- 1 = Stop mode recovery after 32 BUSCLKX4 cycles
- 0 = Stop mode recovery after 4096 BUSCLKX4 cycles

NOTE

Exiting stop mode by an LVI reset will result in the long stop recovery.

When using the LVI during normal operation but disabling during stop mode, the LVI will have an enable time of t_{EN} . The system stabilization time for power-on reset and long stop recovery (both 4096 BUSCLKX4 cycles) gives a delay longer than the LVI enable time for these startup scenarios. There is no period where the MCU is not protected from a low-power condition. However, when using the short stop recovery configuration option, the 32 BUSCLKX4 delay must be greater than the LVI's turn on time to avoid a period in startup where the LVI is not protecting the MCU.

STOP — STOP Instruction Enable Bit

STOP enables the STOP instruction.

- 1 = STOP instruction enabled
- 0 = STOP instruction treated as illegal opcode

COPD — COP Disable Bit

COPD disables the COP module.

- 1 = COP module disabled
- 0 = COP module enabled

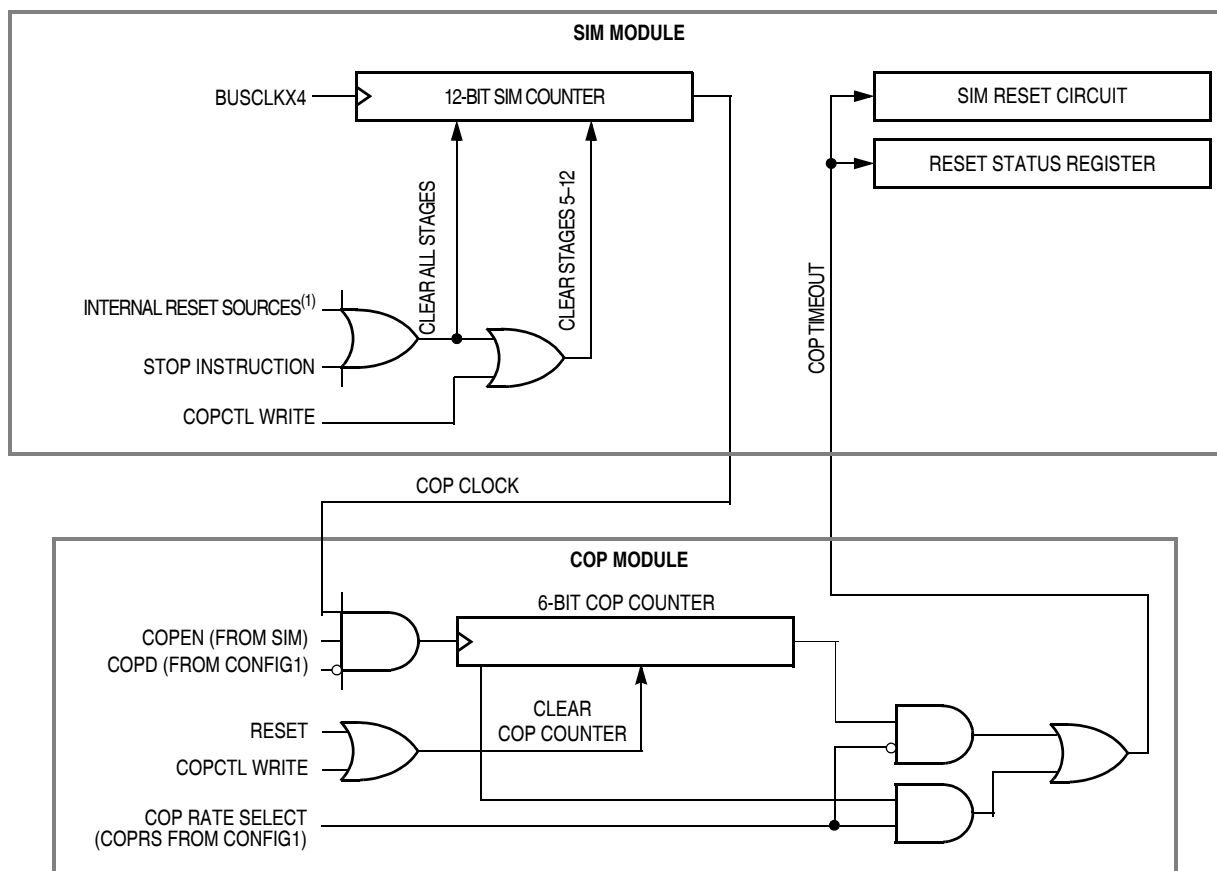
Chapter 6

Computer Operating Properly (COP)

6.1 Introduction

The computer operating properly (COP) module contains a free-running counter that generates a reset if allowed to overflow. The COP module helps software recover from runaway code. Prevent a COP reset by clearing the COP counter periodically. The COP module can be disabled through the COPD bit in the configuration 1 (CONFIG1) register.

6.2 Functional Description



1. See [Chapter 13 System Integration Module \(SIM\)](#) for more details.

Figure 6-1. COP Block Diagram

8.8 Registers

The IRQ status and control register (INTSCR) controls and monitors operation of the IRQ module. The INTSCR:

- Shows the state of the IRQ flag
- Clears the IRQ latch
- Masks the IRQ interrupt request
- Controls triggering sensitivity of the $\overline{\text{IRQ}}$ interrupt pin

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	0	0	0	0	IRQF	0	IMASK	MODE
Write:						ACK		
Reset:	0	0	0	0	0	0	0	0

 = Unimplemented

Figure 8-3. IRQ Status and Control Register (INTSCR)

IRQF — IRQ Flag Bit

This read-only status bit is set when the IRQ interrupt is pending.

1 = $\overline{\text{IRQ}}$ interrupt pending

0 = $\overline{\text{IRQ}}$ interrupt not pending

ACK — IRQ Interrupt Request Acknowledge Bit

Writing a 1 to this write-only bit clears the IRQ latch. ACK always reads 0.

IMASK — IRQ Interrupt Mask Bit

Writing a 1 to this read/write bit disables the IRQ interrupt request.

1 = IRQ interrupt request disabled

0 = IRQ interrupt request enabled

MODE — IRQ Edge/Level Select Bit

This read/write bit controls the triggering sensitivity of the $\overline{\text{IRQ}}$ pin.

1 = $\overline{\text{IRQ}}$ interrupt request on falling edges and low levels

0 = $\overline{\text{IRQ}}$ interrupt request on falling edges only

Oscillator (OSC) Module

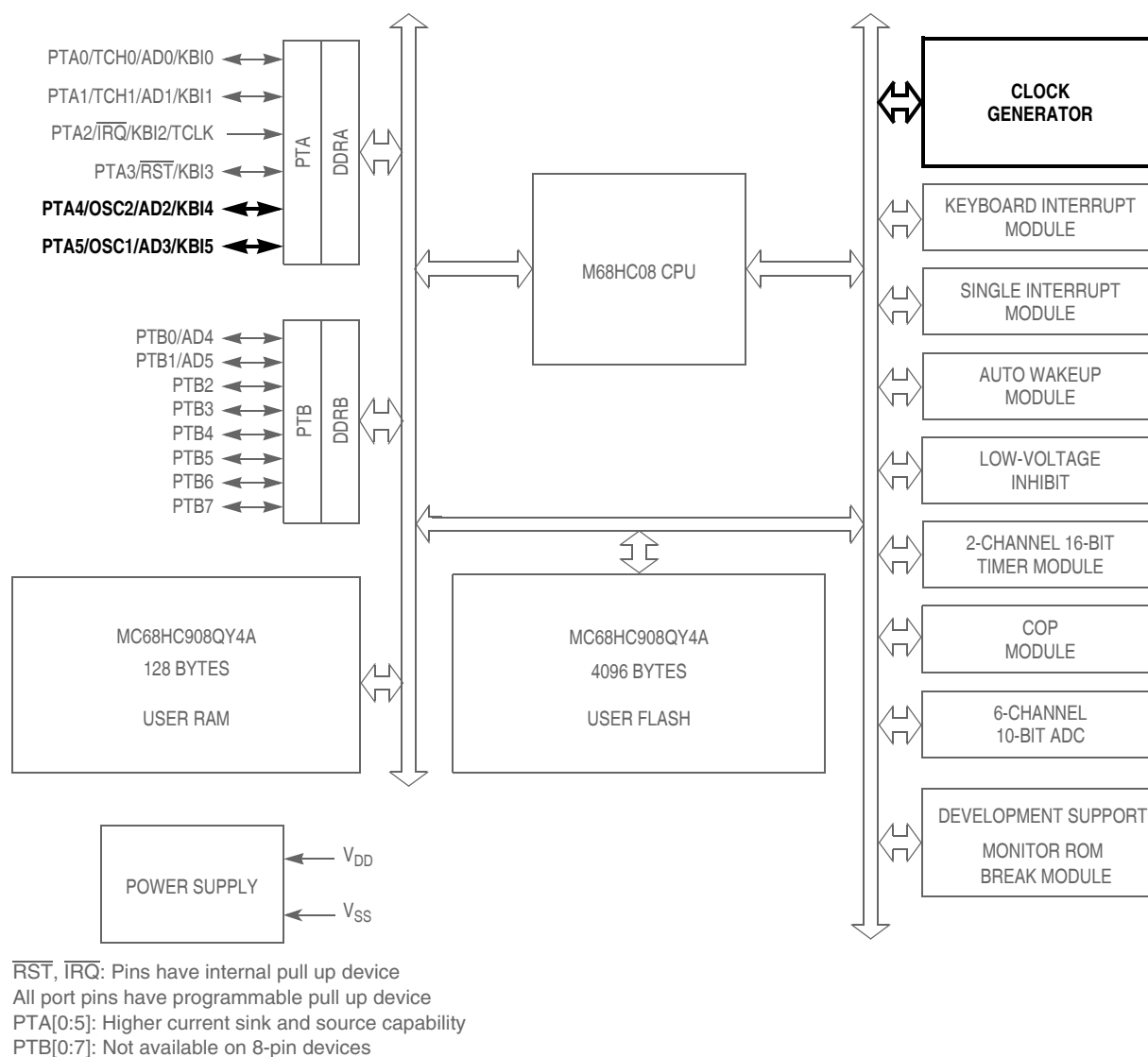


Figure 11-1. Block Diagram Highlighting OSC Block and Pins

11.3.1 Internal Signal Definitions

The following signals and clocks are used in the functional description and figures of the OSC module.

11.3.1.1 Oscillator Enable Signal (*SIMOSCEN*)

The SIMOSCEN signal comes from the system integration module (SIM) and disables the XTAL oscillator circuit, the RC oscillator, or the internal oscillator in stop mode. OSCENINSTOP in the configuration register can be used to override this signal.

13.3.1 Bus Timing

In user mode, the internal bus frequency is the oscillator frequency (BUSCLKX4) divided by four.

13.3.2 Clock Start-Up from POR

When the power-on reset module generates a reset, the clocks to the CPU and peripherals are inactive and held in an inactive phase until after the 4096 BUSCLKX4 cycle POR time out has completed. The IBUS clocks start upon completion of the time out.

13.3.3 Clocks in Stop Mode and Wait Mode

Upon exit from stop mode by an interrupt or reset, the SIM allows BUSCLKX4 to clock the SIM counter. The CPU and peripheral clocks do not become active until after the stop delay time out. This time out is selectable as 4096 or 32 BUSCLKX4 cycles. See [13.7.2 Stop Mode](#).

In wait mode, the CPU clocks are inactive. The SIM also produces two sets of clocks for other modules. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

13.4 Reset and System Initialization

The MCU has these reset sources:

- Power-on reset module (POR)
- External reset pin ($\overline{\text{RST}}$)
- Computer operating properly module (COP)
- Low-voltage inhibit module (LVI)
- Illegal opcode
- Illegal address

All of these resets produce the vector \$FFFE–FFFF (\$FEFE–FEFF in monitor mode) and assert the internal reset signal (IRST). IRST causes all registers to be returned to their default values and all modules to be returned to their reset states.

An internal reset clears the SIM counter (see [13.5 SIM Counter](#)), but an external reset does not. Each of the resets sets a corresponding bit in the SIM reset status register (SRSR). See [13.8 SIM Registers](#).

13.4.1 External Pin Reset

The $\overline{\text{RST}}$ pin circuits include an internal pullup device. Pulling the asynchronous $\overline{\text{RST}}$ pin low halts all processing. The PIN bit of the SIM reset status register (SRSR) is set as long as $\overline{\text{RST}}$ is held low for at least the minimum t_{RL} time. [Figure 13-3](#) shows the relative timing. The $\overline{\text{RST}}$ pin function is only available if the RSTEN bit is set in the CONFIG2 register.

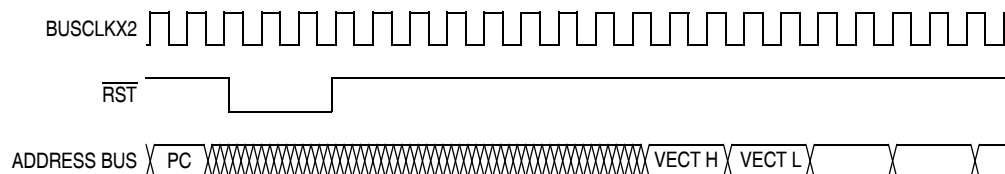


Figure 13-3. External Reset Timing

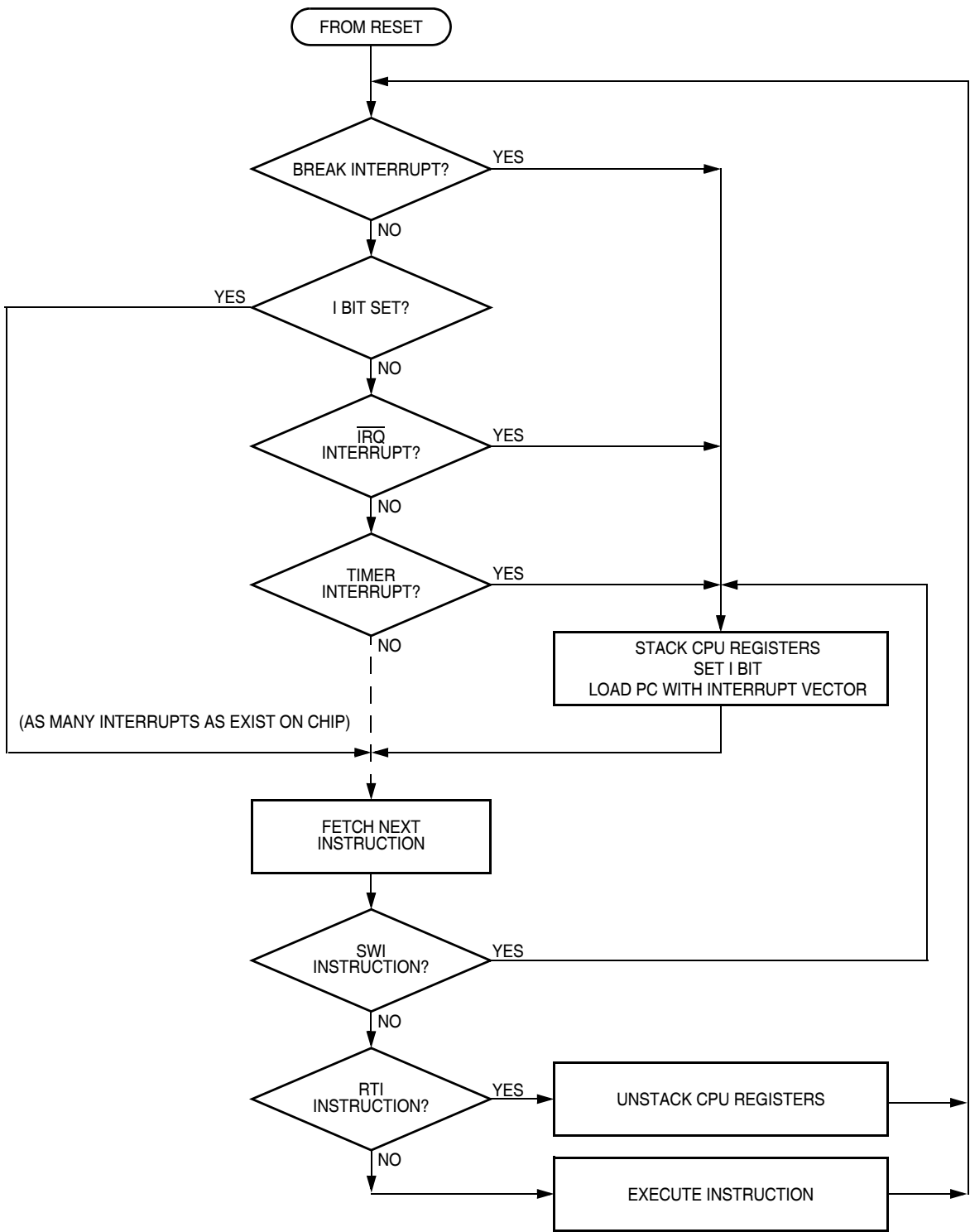


Figure 13-7. Interrupt Processing

the end of the current pulse) could cause two output compares to occur in the same counter overflow period.

14.3.3.2 Buffered Output Compare

Channels 0 and 1 can be linked to form a buffered output compare channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The output compare value in the TIM channel 0 registers initially controls the output on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the output after the TIM overflows. At each subsequent overflow, the TIM channel registers (0 or 1) that control the output are the ones written to last. TSC0 controls and monitors the buffered output compare function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered output compare operation, do not write new output compare values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered output compares.

14.3.4 Pulse Width Modulation (PWM)

By using the toggle-on-overflow feature with an output compare channel, the TIM can generate a PWM signal. The value in the TIM counter modulo registers determines the period of the PWM signal. The channel pin toggles when the counter reaches the value in the TIM counter modulo registers. The time between overflows is the period of the PWM signal.

As [Figure 14-3](#) shows, the output compare value in the TIM channel registers determines the pulse width of the PWM signal. The time between overflow and output compare is the pulse width. Program the TIM to clear the channel pin on output compare if the polarity of the PWM pulse is 1 (ELSxA = 0). Program the TIM to set the pin if the polarity of the PWM pulse is 0 (ELSxA = 1).

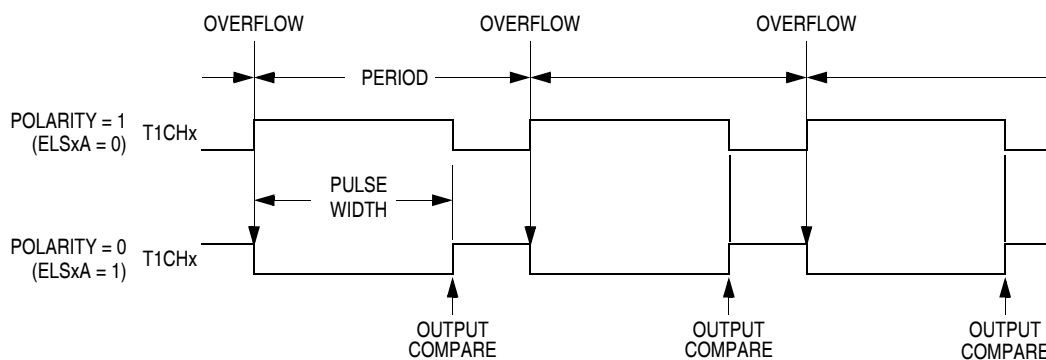


Figure 14-3. PWM Period and Pulse Width

The value in the TIM counter modulo registers and the selected prescaler output determines the frequency of the PWM output. The frequency of an 8-bit PWM signal is variable in 256 increments. Writing \$00FF (255) to the TIM counter modulo registers produces a PWM period of 256 times the internal bus clock period if the prescaler select value is 000. See [14.8.1 TIM Status and Control Register](#).

14.8.4 TIM Channel Status and Control Registers

Each of the TIM channel status and control registers does the following:

- Flags input captures and output compares
- Enables input capture and output compare interrupts
- Selects input capture, output compare, or PWM operation
- Selects high, low, or toggling output on output compare
- Selects rising edge, falling edge, or any edge as the active input capture trigger
- Selects output toggling on TIM overflow
- Selects 0% and 100% PWM duty cycle
- Selects buffered or unbuffered output compare/PWM operation

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
Write:	0							
Reset:	0	0	0	0	0	0	0	0

Figure 14-9. TIM Channel 0 Status and Control Register (TSC0)

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
Write:	0							
Reset:	0	0	0	0	0	0	0	0

 = Unimplemented

Figure 14-10. TIM Channel 1 Status and Control Register (TSC1)

CHxF — Channel x Flag Bit

When channel x is an input capture channel, this read/write bit is set when an active edge occurs on the channel x pin. When channel x is an output compare channel, CHxF is set when the value in the counter registers matches the value in the TIM channel x registers.

Clear CHxF by reading the TSCx register with CHxF set and then writing a 0 to CHxF. If another interrupt request occurs before the clearing sequence is complete, then writing 0 to CHxF has no effect. Therefore, an interrupt request cannot be lost due to inadvertent clearing of CHxF.

Writing a 1 to CHxF has no effect.

- 1 = Input capture or output compare on channel x
- 0 = No input capture or output compare on channel x

CHxIE — Channel x Interrupt Enable Bit

This read/write bit enables TIM interrupt service requests on channel x.

- 1 = Channel x interrupt requests enabled
- 0 = Channel x interrupt requests disabled

MSxB — Mode Select Bit B

This read/write bit selects buffered output compare/PWM operation. MSxB exists only in the TSC0.

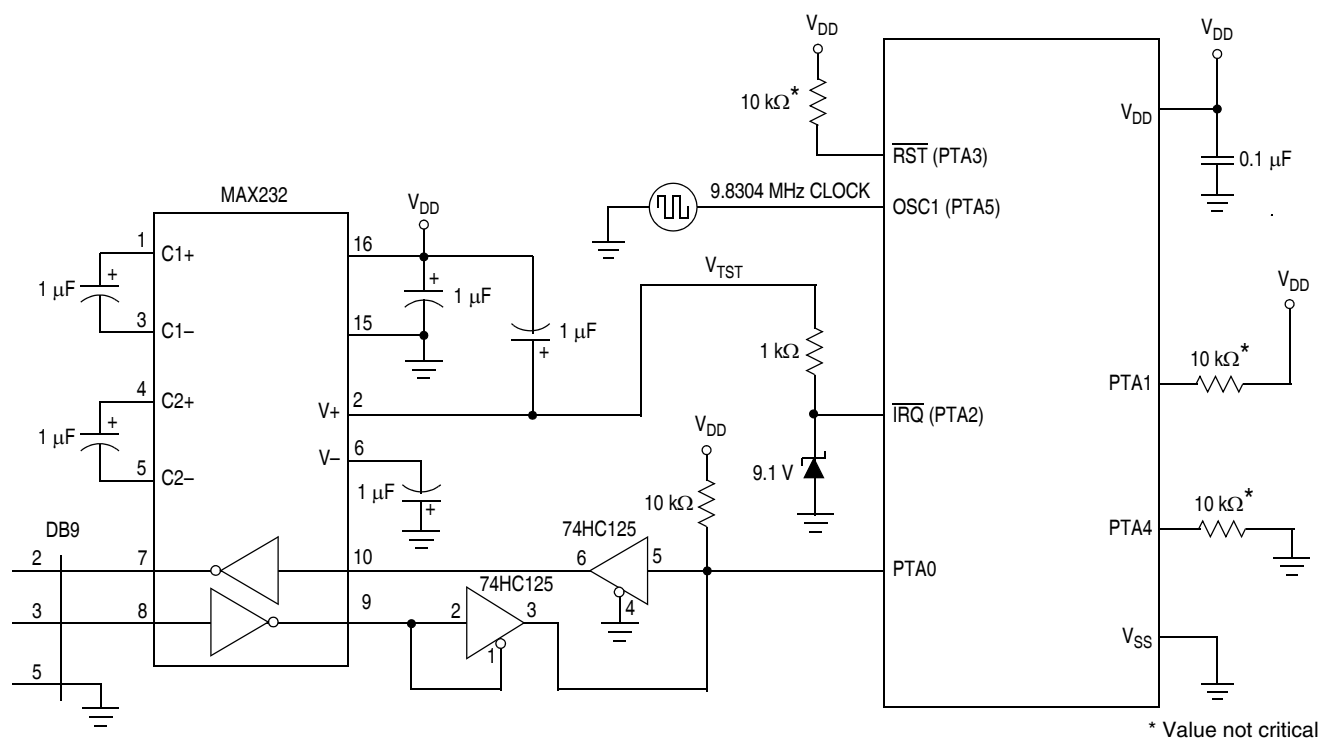


Figure 15-10. Monitor Mode Circuit (External Clock, with High Voltage)

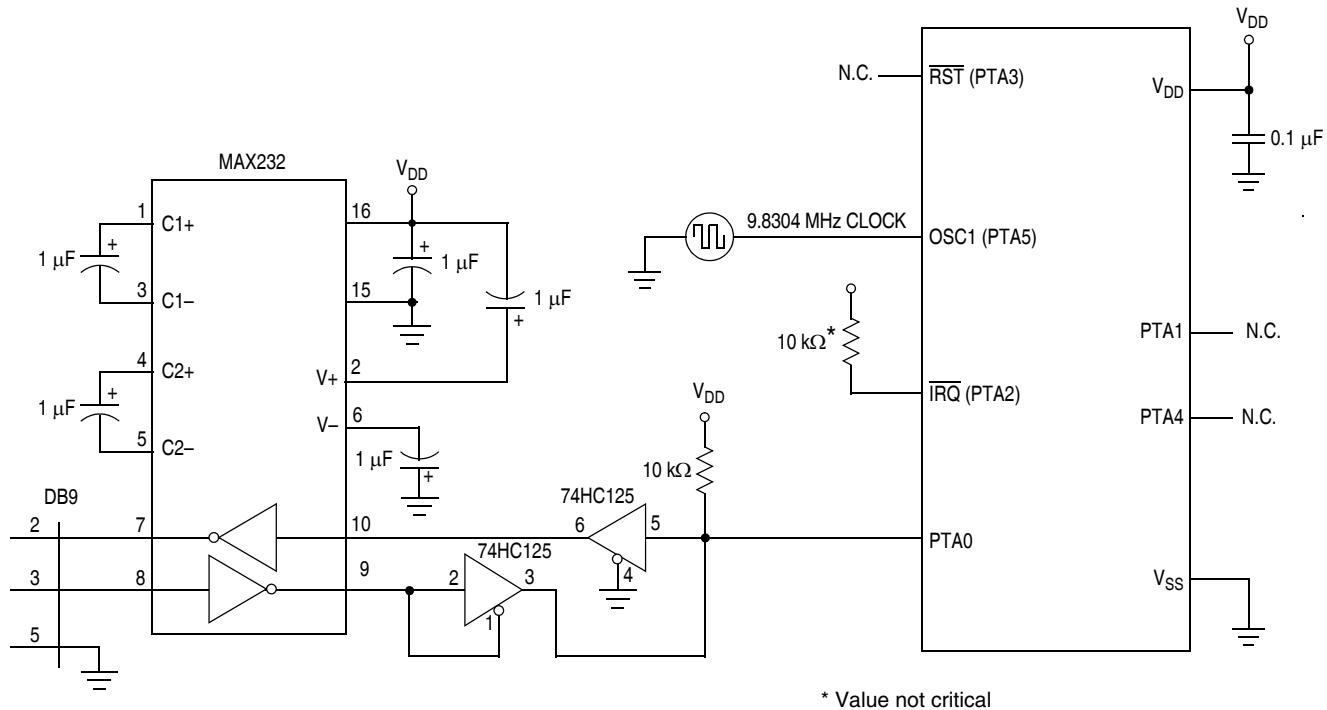


Figure 15-11. Monitor Mode Circuit (External Clock, No High Voltage)

Table 15-1. Monitor Mode Signal Requirements and Options

Mode	$\overline{\text{IRQ}}$ (PTA2)	$\overline{\text{RST}}$ (PTA3)	Reset Vector	Serial Communi- cation	Mode Selection		COP	Communication Speed			Comments
					PTA0	PTA1	PTA4	External Clock	Bus Frequency	Baud Rate	
Normal Monitor	V_{TST}	V_{DD}	X	1	1	0	Disabled	9.8304 MHz	2.4576 MHz	9600	Provide external clock at OSC1.
Forced Monitor	V_{DD}	X	\$FFFF (blank)	1	X	X	Disabled	9.8304 MHz	2.4576 MHz	9600	Provide external clock at OSC1.
	V_{SS}	X	\$FFFF (blank)	1	X	X	Disabled	X	3.2 MHz (Trimmed)	9600	Internal clock is active.
User	X	X	Not \$FFFF	X	X	X	Enabled	X	X	X	
MON08 Function [Pin No.]	V_{TST} [6]	$\overline{\text{RST}}$ [4]	—	COM [8]	MOD0 [12]	MOD1 [10]	—	OSC1 [13]	—	—	

1. PTA0 must have a pullup resistor to V_{DD} in monitor mode.
2. Communication speed in the table is an example to obtain a baud rate of 9600. Baud rate using external oscillator is bus frequency / 256 and baud rate using internal oscillator is bus frequency / 335.
3. External clock is a 9.8304 MHz oscillator on OSC1.
4. Lowering V_{TST} once monitor mode is entered allows the clock source to be controlled by the OSCSC register.
5. X = don't care
6. MON08 pin refers to P&E Microcomputer Systems' MON08-Cyclone 2 by 8-pin connector.

NC	1	2	GND
NC	3	4	RST
NC	5	6	IRQ
NC	7	8	PTA0
NC	9	10	PTA4
NC	11	12	PTA1
OSC1	13	14	NC
V_{DD}	15	16	NC

15.3.1.1 Normal Monitor Mode

$\overline{\text{RST}}$ and OSC1 functions will be active on the PTA3 and PTA5 pins respectively as long as V_{TST} is applied to the $\overline{\text{IRQ}}$ pin. If the $\overline{\text{IRQ}}$ pin is lowered (no longer V_{TST}) then the chip will still be operating in monitor mode, but the pin functions will be determined by the settings in the configuration registers (see [Chapter 5 Configuration Register \(CONFIG\)](#)) when V_{TST} was lowered. With V_{TST} lowered, the BIH and BIL instructions will read the $\overline{\text{IRQ}}$ pin state only if IRQEN is set in the CONFIG2 register.

If monitor mode was entered with V_{TST} on $\overline{\text{IRQ}}$, then the COP is disabled as long as V_{TST} is applied to $\overline{\text{IRQ}}$.

15.3.1.2 Forced Monitor Mode

If entering monitor mode without high voltage on $\overline{\text{IRQ}}$, then startup port pin requirements and conditions, (PTA1/PTA4) are not in effect. This is to reduce circuit requirements when performing in-circuit programming.

16.9 Typical 3-V Output Drive Characteristics

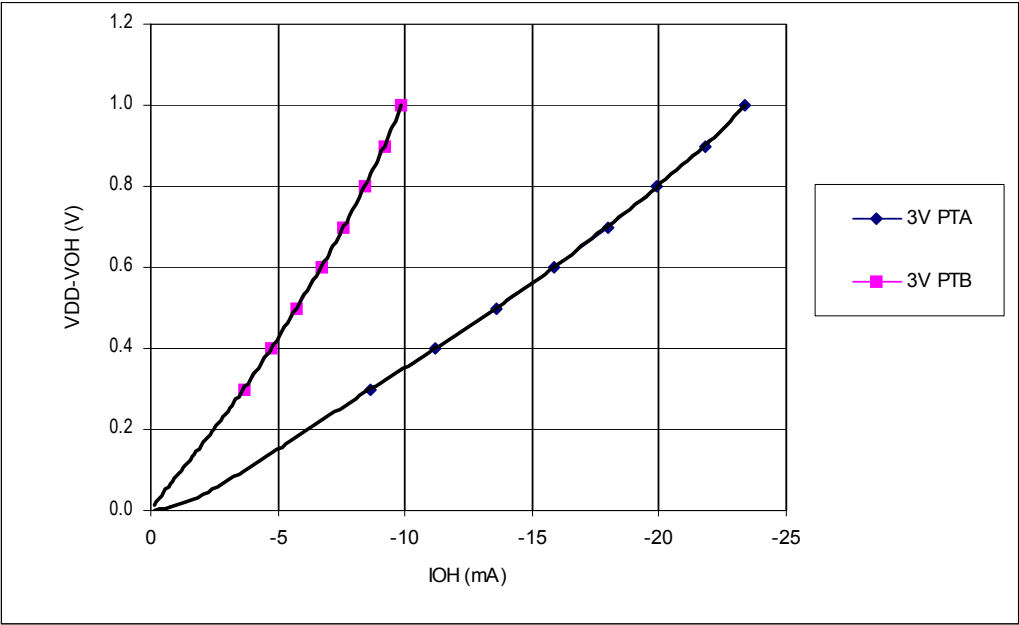


Figure 16-4. Typical 3-Volt Output High Voltage versus Output High Current (25°C)

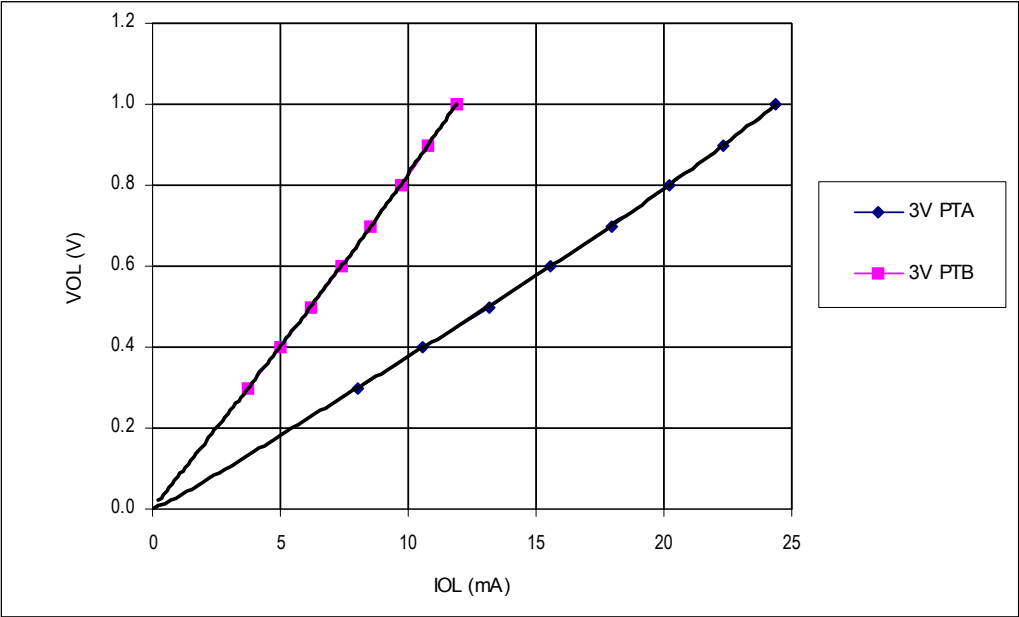


Figure 16-5. Typical 3-Volt Output Low Voltage versus Output Low Current (25°C)

16.11 Oscillator Characteristics

Characteristic	Symbol	Min	Typ	Max	Unit
Internal oscillator frequency ⁽¹⁾ ICFS1:ICFS0 = 00 ICFS1:ICFS0 = 01 ICFS1:ICFS0 = 10 (not allowed if $V_{DD} < 2.7V$)	f_{INTCLK}	— — —	4 8 12.8	— — —	MHz
Trim accuracy ⁽²⁾⁽³⁾	Δ_{TRIM_ACC}	—	± 0.4	—	%
Deviation from trimmed Internal oscillator ⁽³⁾⁽⁴⁾ 4, 8, 12.8MHz, $V_{DD} \pm 10\%$, 0 to 70°C 4, 8, 12.8MHz, $V_{DD} \pm 10\%$, -40 to 125°C	Δ_{INT_TRIM}	— —	± 2 —	— ± 5	%
External RC oscillator frequency, RCCLK ⁽¹⁾⁽³⁾	f_{RCCLK}	2	—	10	MHz
External clock reference frequency ⁽¹⁾⁽⁵⁾⁽⁶⁾ $V_{DD} \geq 4.5V$ $V_{DD} < 4.5V$	f_{OSCCLK}	dc dc	—	32 16	MHz
RC oscillator external resistor ⁽³⁾ $V_{DD} = 5V$ $V_{DD} = 3V$	R_{EXT}	See Figure 16-7 See Figure 16-8			—
Crystal frequency, XTALCLK ⁽¹⁾⁽⁷⁾⁽⁸⁾ ECFS1:ECFS0 = 00 ($V_{DD} \geq 4.5V$) ECFS1:ECFS0 = 00 ECFS1:ECFS0 = 01 ECFS1:ECFS0 = 10	f_{OSCCLK}	8 8 1 30	—	32 16 8 100	MHz MHz MHz kHz
ECFS1:ECFS0 = 00 ⁽⁹⁾ Feedback bias resistor Crystal load capacitance ⁽¹⁰⁾ Crystal capacitors ⁽¹⁰⁾	R_B C_L C_1, C_2	— — —	1 20 (2 x C_L) – 5pF	— — —	MΩ pF pF
ECFS1:ECFS0 = 01 ⁽⁹⁾ Crystal series damping resistor $f_{OSCCLK} = 1MHz$ $f_{OSCCLK} = 4MHz$ $f_{OSCCLK} = 8MHz$ Feedback bias resistor Crystal load capacitance ⁽¹⁰⁾ Crystal capacitors ⁽¹⁰⁾	R_S R_B C_L C_1, C_2	— — — — — — —	20 10 0 5 18 (2 x C_L) – 10 pF	— — — — — —	kΩ kΩ kΩ MΩ pF pF
AWU module internal RC oscillator frequency	f_{INTRC}	—	32	—	kHz

1. Bus frequency, f_{OP} , is oscillator frequency divided by 4.
2. Factory trimmed to provided 12.8MHz accuracy requirement ($\pm 5\%$, @25°C) for forced monitor mode communication. User should trim in-circuit to obtain the most accurate internal oscillator frequency for the application.
3. Values are based on characterization results, not tested in production.
4. Deviation values assumes trimming in target application @25°C and midpoint of voltage range, for example 5.0 V for 5 V $\pm 10\%$ operation.
5. No more than 10% duty cycle deviation from 50%.
6. When external oscillator clock is greater than 1MHz, ECFS1:ECFS0 must be 00 or 01
7. Use fundamental mode only, do **not** use overtone crystals or overtone ceramic resonators
8. Due to variations in electrical properties of external components such as, ESR and Load Capacitance, operation above 16 MHz is not guaranteed for all crystals or ceramic resonators. Operation above 16 MHz requires that a Negative Resistance Margin (NRM) characterization and component optimization be performed by the crystal or ceramic resonator vendor for every different type of crystal or ceramic resonator which will be used. This characterization and optimization must be performed at the extremes of voltage and temperature which will be applied to the microcontroller in the application. The NRM must meet or exceed 10x the maximum ESR of the crystal or ceramic resonator for acceptable performance.
9. Do not use damping resistor when ECFS1:ECFS0 = 00 or 10
10. Consult crystal vendor data sheet.

16.12 Supply Current Characteristics

Characteristic ⁽¹⁾	Voltage	Bus Frequency (MHz)	Symbol	Typ ⁽²⁾	Max	Unit
Run mode V_{DD} supply current ⁽³⁾	5.0 3.0	3.2 3.2	$R_{I_{DD}}$	6.0 3.1	7.0 3.8	mA
Wait mode V_{DD} supply current ⁽⁴⁾	5.0 3.0	3.2 3.2	$W_{I_{DD}}$	1.8 1.1	2.5 1.75	mA
Stop mode V_{DD} supply current ⁽⁵⁾ –40 to 85°C –40 to 105°C ⁽⁶⁾ –40 to 125°C 25°C with auto wake-up enabled Incremental current with LVI enabled at 25°C	5.0		$S_{I_{DD}}$	0.5 — — 20 150	1.2 2.0 5.0 — —	μA
Stop mode V_{DD} supply current ⁽⁴⁾ –40 to 85°C –40 to 105°C ⁽⁶⁾ –40 to 125°C 25°C with auto wake-up enabled Incremental current with LVI enabled at 25°C	3.0			0.36 — — 4 130	1.0 1.2 4.0 — —	μA

1. $V_{SS} = 0$ Vdc, $T_A = T_L$ to T_H , unless otherwise noted.

2. Typical values reflect average measurement at 25°C only.

3. Run (operating) I_{DD} measured using trimmed internal oscillator, ADC off, all modules enabled. All pins configured as inputs and tied to 0.2 V from rail.

4. Wait I_{DD} measured using trimmed internal oscillator, ADC off, all modules enabled. All pins configured as inputs and tied to 0.2 V from rail.

5. Stop I_{DD} measured with all pins configured as inputs and tied to 0.2 V from rail. On the 8-pin versions, port B is configured as inputs with pullups enabled.

6. For automotive applications only.

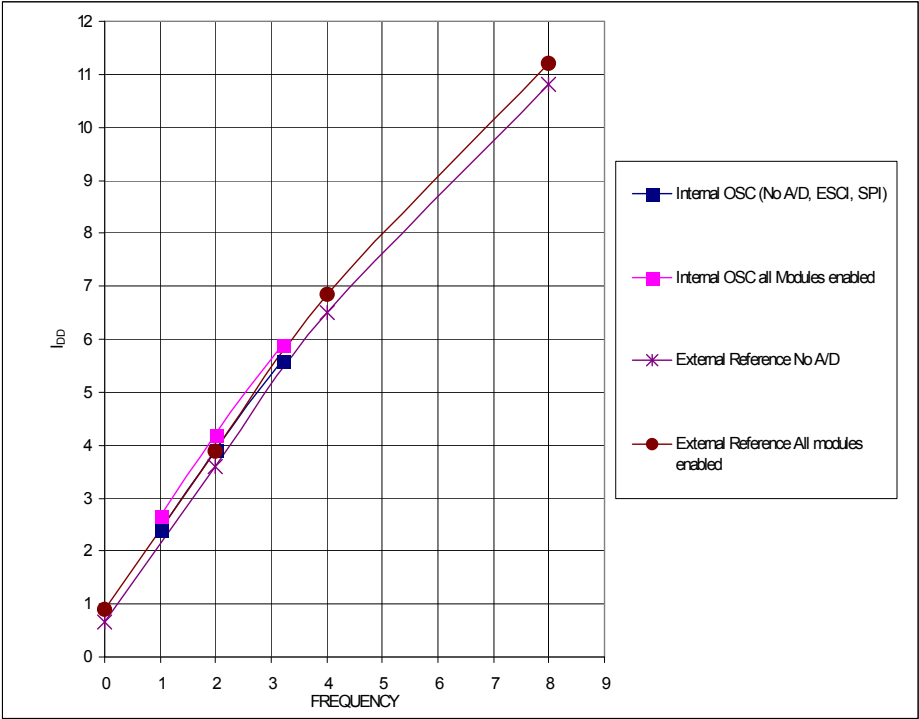


Figure 16-9. Typical 5-Volt Run Current versus Bus Frequency (25°C)

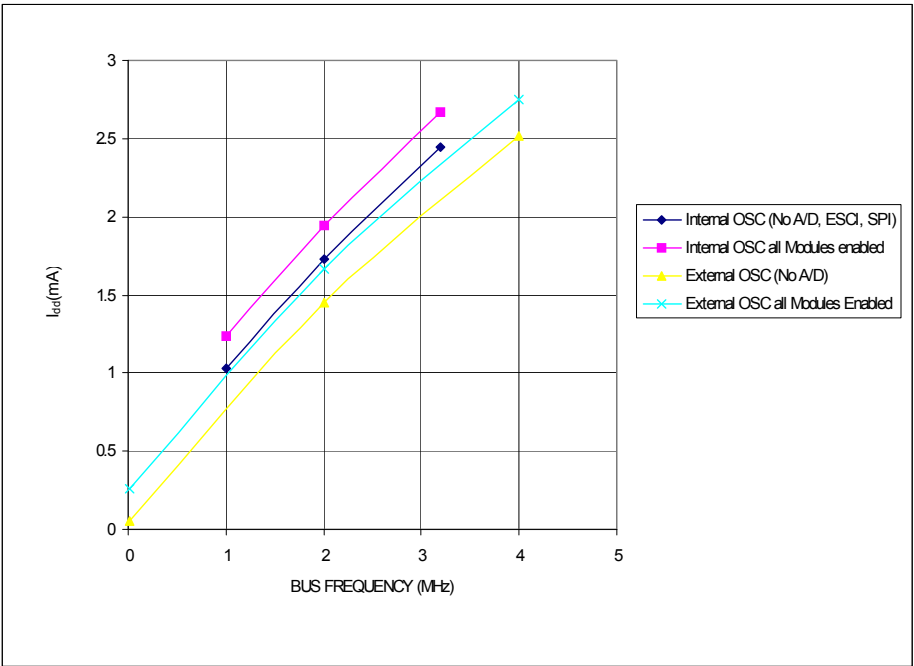


Figure 16-10. Typical 3-Volt Run Current versus Bus Frequency (25°C)

